

Zenglin Wang

List of Publications by Year in descending order

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76
papers

1,964
citations

230014

27
h-index

325983

40
g-index

76
all docs

76
docs citations

76
times ranked

2251
citing authors

#	ARTICLE	IF	CITATIONS
1	Analysis of multiple-phytohormones during fruit development in strawberry by using miniaturized dispersive solid-phase extraction based on ionic liquid-functionalized carbon fibers. <i>Journal of Food Composition and Analysis</i> , 2022, 106, 104262.	1.9	3
2	Vibration and Buckling Analysis of Piezoelectric Nanowires Based on Surface Energy Density. <i>Acta Mechanica Solida Sinica</i> , 2021, 34, 425-436.	1.0	9
3	Ni-based 3D hierarchical heterostructures achieved by selective electrodeposition as a bifunctional electrocatalyst for overall water splitting. <i>Electrochimica Acta</i> , 2021, 379, 138042.	2.6	26
4	Hepatitis B virus evades immune recognition via RNA adenosine deaminase ADAR1-mediated viral RNA editing in hepatocytes. <i>Cellular and Molecular Immunology</i> , 2021, 18, 1871-1882.	4.8	26
5	Electrodeposited of ultrathin VO _x -doped NiFe layer on porous NiCo phosphide for efficient overall water splitting. <i>Applied Physics Letters</i> , 2021, 119, .	1.5	6
6	Highly isolated Pt NPs embedded in porous TiO ₂ derived from MIL-125 with enhanced photocatalytic hydrogen production activity. <i>Journal of Catalysis</i> , 2021, 402, 289-299.	3.1	17
7	Boussinesq problem with the surface effect based on surface energy density. <i>International Journal of Mechanics and Materials in Design</i> , 2020, 16, 633-645.	1.7	3
8	Pulsed electrodeposition of well-ordered nanoporous Cu-doped Ni arrays promotes high-efficiency overall hydrazine splitting. <i>Journal of Materials Chemistry A</i> , 2020, 8, 21084-21093.	5.2	36
9	Simultaneous determination of multiple phytohormones in tomato by ionic liquid-functionalized carbon fibers-based solid-phase microextraction coupled with liquid chromatography-mass spectrometry. <i>Analytica Chimica Acta</i> , 2020, 1137, 143-155.	2.6	23
10	Electrochemical modification and tuning Ni/Ni(OH) ₂ @Ag heterogeneous interface for efficient electrocatalytic hydrogen and oxygen evolution reactions. <i>Electrochimica Acta</i> , 2020, 341, 136051.	2.6	18
11	HF promoted increased nitrogen doping in TiO ₂ (B) photocatalyst. <i>Chemical Communications</i> , 2020, 56, 5609-5612.	2.2	13
12	Monodispersed silver-palladium nanoparticles for ethanol oxidation reaction achieved by controllable electrochemical synthesis from ionic liquid microemulsions. <i>Journal of Colloid and Interface Science</i> , 2019, 557, 450-457.	5.0	18
13	Surface Assistant Charge Separation in PEC Cu ₂ S@Ni/Cu ₂ O Cathode. <i>ACS Applied Materials & Interfaces</i> , 2019, 11, 34000-34009.	4.0	18
14	Fabrication of 3D microporous amorphous metallic phosphides for high-efficiency hydrogen evolution reaction. <i>Electrochimica Acta</i> , 2019, 306, 651-659.	2.6	48
15	Hierarchical nanoporous Ni(Cu) alloy anchored on amorphous NiFeP as efficient bifunctional electrocatalysts for hydrogen evolution and hydrazine oxidation. <i>Journal of Catalysis</i> , 2019, 373, 180-189.	3.1	85
16	Ultralow Fe ^{III} Ion Doping Triggered Generation of Ni ₃ S ₂ Ultrathin Nanosheet for Enhanced Oxygen Evolution Reaction. <i>ChemCatChem</i> , 2019, 11, 2011-2016.	1.8	29
17	Surface modification of polyimide by combining swelling and TiO ₂ photocatalytic treatments for adhesion improvement of electroless Cu. <i>Journal of Adhesion Science and Technology</i> , 2019, 33, 371-381.	1.4	7
18	Fabrication of TiO ₂ (B)/Anatase Heterophase Junctions at High Temperature via Stabilizing the Surface of TiO ₂ (B) for Enhanced Photocatalytic Activity. <i>Journal of Physical Chemistry C</i> , 2019, 123, 1779-1789.	1.5	43

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19	Improved electrochemical performance of nickel-cobalt hydroxides by electrodeposition of interlayered reduced graphene oxide. <i>International Journal of Hydrogen Energy</i> , 2019, 44, 3658-3667.	3.8	13
20	Robust Conductive Micropatterns on PTFE Achieved via Selective UV-Induced Graft Copolymerization for Flexible Electronic Applications. <i>ACS Applied Materials & Interfaces</i> , 2019, 11, 5517-5525.	4.0	14
21	Synergistic Nanotubular Copper-Doped Nickel Catalysts for Hydrogen Evolution Reactions. <i>Small</i> , 2018, 14, e1704137.	5.2	111
22	Electrodeposition of porous MoO ₄ ²⁻ -doped NiFe nanosheets for highly efficient electrocatalytic oxygen evolution reactions. <i>Electrochimica Acta</i> , 2018, 260, 477-482.	2.6	33
23	Soft Template-Directed Reactions: One-Pot Synthetic Route for Bimetallic Core-Satellite-Shell Structured Electrocatalytic Nanospheres. <i>ChemCatChem</i> , 2018, 10, 2546-2550.	1.8	1
24	Copper (0) Doping Makes Cobalt-Nickel Hydroxide a High-Efficiency Catalyst for Hydrogen Evolution Reaction. <i>Journal of the Electrochemical Society</i> , 2018, 165, H866-H871.	1.3	12
25	Bifunctional Copper-Doped Nickel Catalysts Enable Energy-Efficient Hydrogen Production via Hydrazine Oxidation and Hydrogen Evolution Reduction. <i>ACS Sustainable Chemistry and Engineering</i> , 2018, 6, 12746-12754.	3.2	68
26	Photocatalytic Surface Modification of PI Film for Electroless Copper Plating. <i>Advances in Condensed Matter Physics</i> , 2018, 2018, 1-8.	0.4	3
27	Fabrication of TiO ₂ (B)/anatase heterophase junctions in nanowires via a surface-preferred phase transformation process for enhanced photocatalytic activity. <i>Chinese Journal of Catalysis</i> , 2018, 39, 1500-1510.	6.9	33
28	Effect of the molecular chains grafted on graphene nanosheets on the properties of poly(lactide) nanocomposites. <i>Polymer Composites</i> , 2017, 38, 5-12.	2.3	19
29	Fabrication of Nanoporous Nickel-Iron Hydroxylphosphate Composite as Bifunctional and Reversible Catalyst for Highly Efficient Intermittent Water Splitting. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 35837-35846.	4.0	76
30	Electrodeposition of Cobalt Nickel Hydroxide Composite as a High-Efficiency Catalyst for Hydrogen Evolution Reactions. <i>Journal of the Electrochemical Society</i> , 2017, 164, H587-H592.	1.3	27
31	2-Mercaptopyridine as a new leveler for bottom-up filling of micro-vias in copper electroplating. <i>Electrochimica Acta</i> , 2016, 208, 33-38.	2.6	53
32	Electrochemical Synthesis of Continuous Controllable Ag Nanoparticles from Quaternary Ionic Liquid Microemulsions and Electrocatalytic Activity. <i>Journal of the Electrochemical Society</i> , 2016, 163, D442-D446.	1.3	6
33	Electrochemical Research of a Stable Electroless Silver Bath. <i>Journal of the Electrochemical Society</i> , 2016, 163, D121-D125.	1.3	12
34	Effect of initial temperature on joint of aluminum alloy to galvanized steel welded by MIG arc brazing-fusion welding process. <i>International Journal of Advanced Manufacturing Technology</i> , 2016, 86, 3135-3143.	1.5	15
35	The effect of TiO ₂ morphology on the surface modification of poly (ethylene) Tj ETQq1 1 0.784314 rgBT/Overlock 10 Tf 50	1.4	9
36	Controllable electrochemical synthesis of Ag nanoparticles in ionic liquid microemulsions. <i>Electrochemistry Communications</i> , 2015, 58, 41-45.	2.3	34

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37	Investigation of Nitrogen Heterocyclic Compounds as Levelers for Electroplating Cu Filling by Electrochemical Method and Quantum Chemical Calculation. <i>Journal of the Electrochemical Society</i> , 2015, 162, D509-D514.	1.3	37
38	Tetrazole Derived Levelers for Filling Electroplated Cu Microvias: Electrochemical Behaviors and Quantum Calculations. <i>Electrochimica Acta</i> , 2015, 178, 546-554.	2.6	36
39	Surface modification of ABS by photocatalytic treatment for electroless copper plating. <i>Journal of Adhesion Science and Technology</i> , 2014, 28, 499-511.	1.4	19
40	A study of bottom-up electroplated copper filling by the potential difference between two rotating speeds of a working electrode. <i>Journal of Electroanalytical Chemistry</i> , 2014, 712, 25-32.	1.9	35
41	Adhesion improvement of electroless copper to PC substrate by a low environmental pollution MnO ₂ •H ₃ PO ₄ •H ₂ SO ₄ •H ₂ O system. <i>International Journal of Adhesion and Adhesives</i> , 2013, 41, 50-56.	1.4	12
42	Study of an environment-friendly surface pretreatment of ABS-polycarbonate surface for adhesion improvement. <i>International Journal of Adhesion and Adhesives</i> , 2013, 44, 243-249.	1.4	36
43	Improvement in the Etching Performance of the Acrylonitrile•Butadiene•Styrene Resin by MnO ₂ •H ₃ PO ₄ •H ₂ SO ₄ Colloid. <i>Langmuir</i> , 2013, 29, 5968-5973.	1.6	20
44	A study of the environmentally friendly polycarbonate surface etching system containing H ₂ SO ₄ •MnO ₂ colloid. <i>Journal of Adhesion Science and Technology</i> , 2013, 27, 1455-1463.	1.4	5
45	A New Surface Etching Method Using MnO ₂ /H ₂ SO ₄ Colloid for Adhesion Improvement of Epoxy Polymer. <i>Journal of Adhesion Science and Technology</i> , 2012, 26, 1407-1417.	1.4	4
46	Preparation of Ag-Nanoparticle-Loaded MnO ₂ Nanosheets and Their Capacitance Behavior. <i>Energy & Fuels</i> , 2012, 26, 618-623.	2.5	82
47	Effect of additive triblock copolymer PEP-3100 on bottom-up filling in electroless copper plating. <i>Russian Journal of Electrochemistry</i> , 2012, 48, 99-103.	0.3	2
48	Adhesion Improvement of ABS Resin to Electroless Copper by H ₂ SO ₄ •MnO ₂ Colloid with Ultrasound-Assisted Treatment. <i>Journal of Adhesion Science and Technology</i> , 2011, 25, 1211-1221.	1.4	22
49	Study of an Environmentally Friendly Surface Etching System of ABS for Improving Adhesion of Electroless Cu film. <i>Journal of the Electrochemical Society</i> , 2011, 158, D664.	1.3	36
50	Comparison of Bottom-up Filling in Electroless Plating with an Addition of PEG, PPG and EPE. <i>Chinese Journal of Chemistry</i> , 2011, 29, 422-426.	2.6	5
51	Design and achievement of a complete bottom-up electroless copper filling for sub-micrometer trenches. <i>Electrochimica Acta</i> , 2011, 56, 3317-3321.	2.6	15
52	A Synergy Effect of 2-MBT and PE-3650 on the Bottom-Up Filling in Electroless Copper Plating. <i>Electrochemical and Solid-State Letters</i> , 2011, 14, D107.	2.2	14
53	Effects of Triethanolamine and K ₄ [Fe(CN) ₆] upon Electroless Copper Plating. <i>Journal of the Electrochemical Society</i> , 2010, 157, D500.	1.3	7
54	First Synergy Effects of SPS and PEG-4000 on the Bottom-Up Filling in Electroless Copper Plating. <i>Journal of the Electrochemical Society</i> , 2010, 157, D546.	1.3	10

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55	Bottom-Up Filling in Electroless Plating with an Addition of PEG-PPG Triblock Copolymers. <i>Electrochemical and Solid-State Letters</i> , 2010, 13, D47.	2.2	19
56	Phase coexistence and high electrical properties in $(K_xNa_{0.96-x}Li_{0.04})(Nb_{0.85}Ta_{0.15})O_3$ piezoelectric ceramics. <i>Journal of Applied Physics</i> , 2009, 105, 054101.	1.1	41
57	Cu Filling Characteristics in Through-Si Via Holes by Electroless Plating with Addition of Inhibitors. <i>ECS Transactions</i> , 2009, 16, 27-32.	0.3	0
58	An Environment-Friendly Surface Pretreatment of ABS Resin Prior to Electroless Plating. <i>Electrochemical and Solid-State Letters</i> , 2009, 12, D92.	2.2	33
59	Characterization of sputtered tungsten nitride film and its application to Cu electroless plating. <i>Microelectronic Engineering</i> , 2008, 85, 395-400.	1.1	25
60	Phase Structure, Microstructure, and Electrical Properties of Sb-Modified $(K, Na, Li)(Nb, Ta)O_3$ Piezoelectric Ceramics. <i>Journal of the American Ceramic Society</i> , 2008, 91, 2211-2216.	1.9	33
61	Phase transitional behavior, microstructure, and electrical properties in Ta-modified $[(K_{0.458}Na_{0.542})_{0.96}Li_{0.04}]_xNbO_3$ lead-free piezoelectric ceramics. <i>Journal of Applied Physics</i> , 2008, 104, .	1.1	72
62	Effects of Li content on the phase structure and electrical properties of lead-free $(K_{0.46-x}Na_{0.54-x}Li_x)(Nb_{0.76}Ta_{0.20}Sb_{0.04})O_3$ ceramics. <i>Applied Physics Letters</i> , 2007, 90, 232905.	1.5	73
63	Bottom-up copper fill with addition of mercapto alkyl carboxylic acid in electroless plating. <i>Electrochimica Acta</i> , 2006, 51, 2442-2446.	2.6	28
64	Bottom-up fill mechanisms of electroless copper plating with addition of mercapto alkyl carboxylic acid. <i>Journal of Vacuum Science & Technology B</i> , 2006, 24, 803.	1.3	21
65	Characterization of Electroless-Plated Cu Film over Pd Catalytic Layer Formed by an Ionized Cluster Beam. <i>Journal of the Electrochemical Society</i> , 2005, 152, C684.	1.3	8
66	Effect of Additives on Hole Filling Characteristics of Electroless Copper Plating. <i>Japanese Journal of Applied Physics</i> , 2004, 43, 7000-7001.	0.8	15
67	Bottom-Up Fill for Submicrometer Copper Via Holes of ULSIs by Electroless Plating. <i>Journal of the Electrochemical Society</i> , 2004, 151, C781.	1.3	70
68	Suppression of native oxide growth in sputtered TaN films and its application to Cu electroless plating. <i>Journal of Applied Physics</i> , 2003, 94, 4697-4701.	1.1	48
69	Influence of Surface Oxide of Sputtered TaN on Displacement Plating of Cu. <i>Japanese Journal of Applied Physics</i> , 2003, 42, 1843-1846.	0.8	15
70	Highly Adhesive Electroless Cu Layer Formation Using an Ultra Thin Ionized Cluster Beam (ICB)-Pd Catalytic Layer for Sub-100 nm Cu Interconnections. <i>Japanese Journal of Applied Physics</i> , 2003, 42, L1223-L1225.	0.8	13
71	Electroless Copper Seed Activated by 1nm ICB-Pd Catalytic Layer for Fine Cu Interconnections. , 2003, , .		0
72	Adhesion improvement of electroless copper to a polyimide film substrate by combining surface microroughening and imide ring cleavage. <i>Journal of Adhesion Science and Technology</i> , 2002, 16, 1027-1040.	1.4	55

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73	Influence of Surface Oxide of Sputtered TaN Film on Displacement Plating of Cu. , 2002, , .		0
74	Syntheses, characterization and crystal structures of 5,14-dihydro-6,8,15,17-tetramethyldibenzo[b,i][1,4,8,11]tetraazacyclotetradecine rare earth(III) complexes. Journal of the Chemical Society Dalton Transactions, 1999, , 1695-1700.	1.1	15
75	Synthesis, characterization and crystal structure of a 6,8,15,17-tetramethyldibenzo [b,i] (1,4,8,11)tetraaza (14)-annulene yttrium (III) complex. Polyhedron, 1998, 17, 4451-4456.	1.0	13
76	Adhesion improvement of ABS resin by MnO ₂ -H ₃ PO ₄ -H ₂ SO ₄ colloid with ultrasound-assisted etching treatment. Journal of Adhesion Science and Technology, 0, , 1-11.	1.4	3